

Features

- FRED (Planar) wafer construction
- Ultrafast recovery time
- Low forward voltage drop, low power losses
- High efficiency operation
- Plastic package has underwriters Laboratory Flammability Classification 94V-0



2018

Package: TO-220-AC

Package: ITO-220-AC

**Mechanical Data**

- Case: Epoxy, Molded
- Weight: 1.9grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 sec
- Shipped 50 units per plastic tube

Maximum Ratings & Electrical Characteristics

(TA=25°C unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	MUR880(F)	UNIT
Maximum repetitive peak reverse voltage			V _{RRM}	800	V
Working peak reverse voltage			V _{RWM}	800	V
Maximum DC blocking voltage			V _{DC}	800	V
Maximum average forward rectified current at T _c =105°C total device per diode			I _{F(AV)}	8	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load per diode			I _{FSM}	150	A
Voltage rate of change (rated V _R)			D _{v/dt}	10000	V/us
Operating junction temperature range			T _J	—55 to+150	°C
Storage temperature range			T _{STG}	—55 to+150	°C
Maximum Reverse Recover Time (If=0.5Amp, IR=1.0Amp,Irec=0.25Amp)	T _{rr}		T _{rr}	60	ns
Maximum instantaneous forward voltage per leg	I _f =8A I _f =8A	T _c =25°C T _c =125°C	V _F	1.80 1.70	V
Maximum reverse current per leg at working peak		T _J =25°C T _J =100°C	I _R	10 500	uA uA

Thermal Characteristics TA=25°C unless otherwise noted

Symbol	Parameter	TYP (TO-220-AC)	TYP (ITO-220-AC)	Unit
R _{θJC}	Thermal Resistance, Junction to Case per Leg	2.0	4.0	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient per Leg	62.5	62.5	°C/W

Note: Pulse test:300us pulse width, duty cycle=2%

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

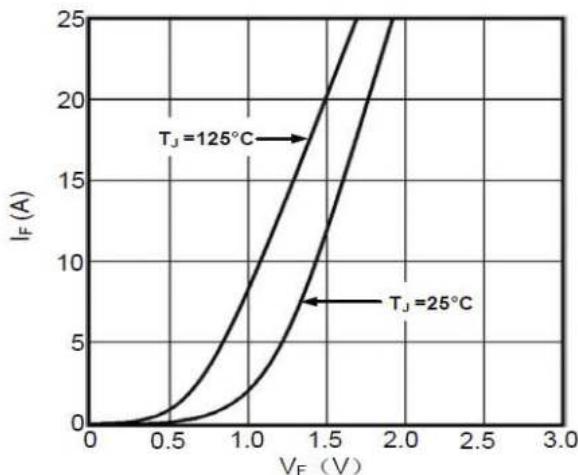


Fig 1. Forward Voltage Drop vs Forward Current

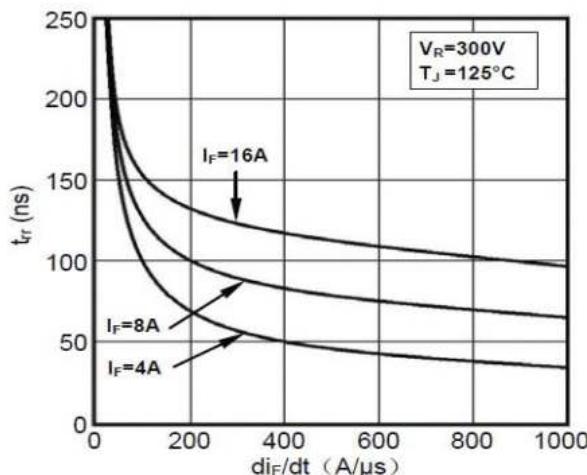


Fig 2. Reverse Recovery Time vs $\frac{di_F}{dt}$

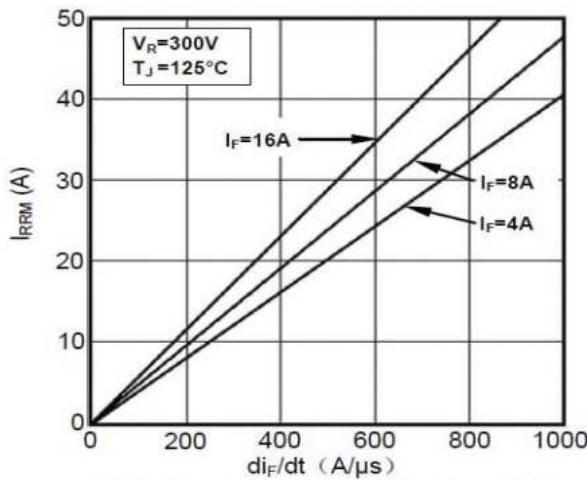


Fig 3. Reverse Recovery Current vs $\frac{di_F}{dt}$

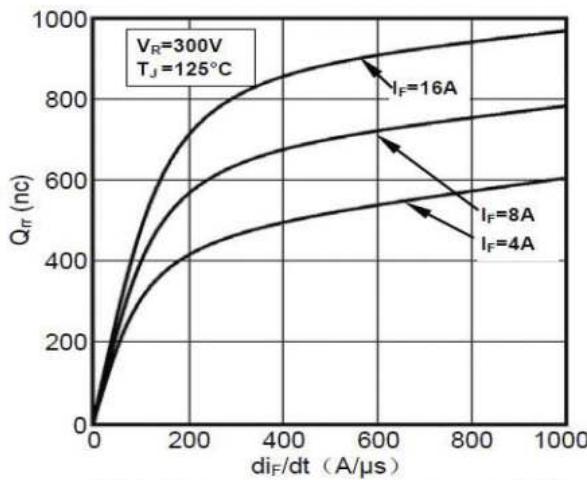


Fig 4. Reverse Recovery Charge vs $\frac{di_F}{dt}$

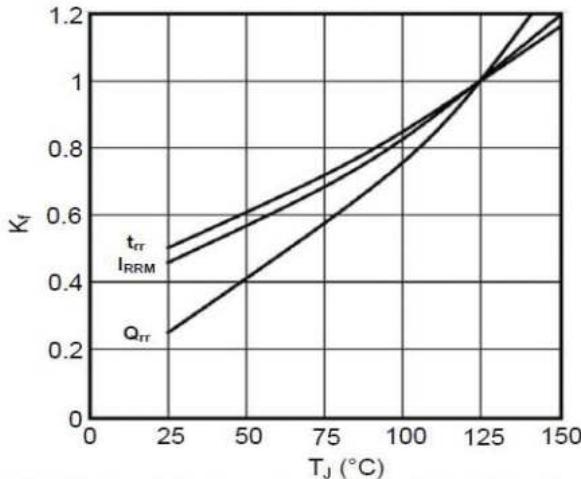


Fig 5. Dynamic Parameters vs Junction Temperature

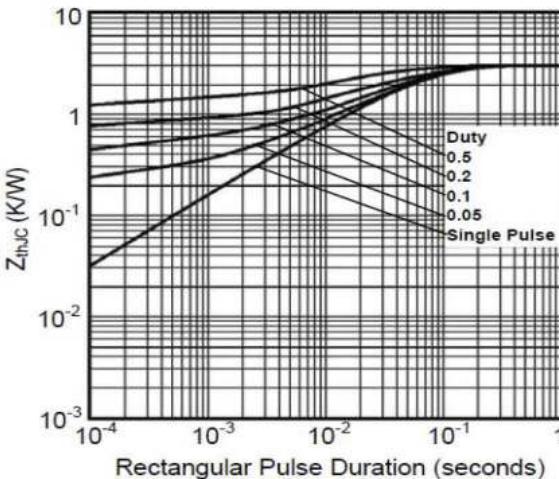
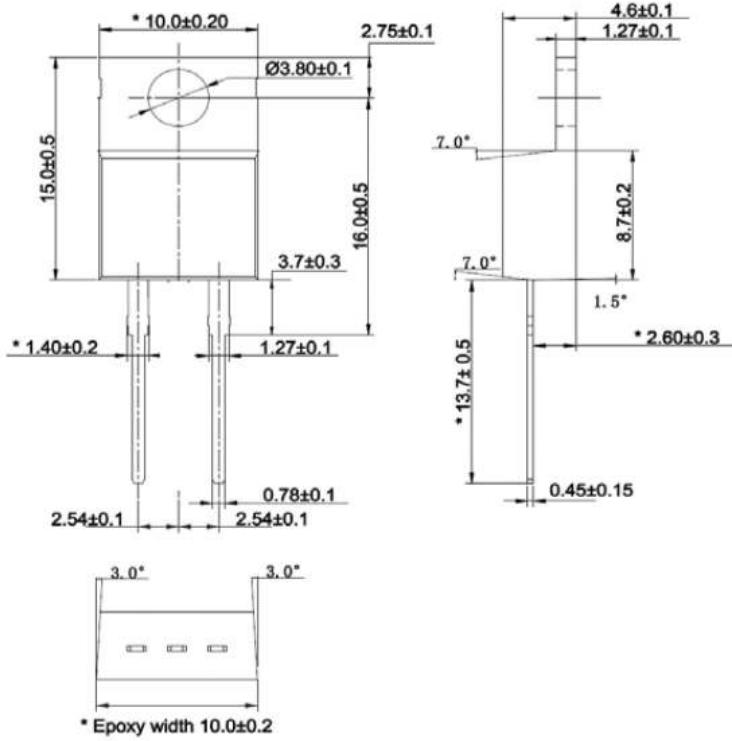


Fig 6. Transient Thermal Impedance

Package Outline Dimensions

Unit: millimeters

TO-220-AC**ITO-220-AC**